

# SN54HC540, SN74HC540 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

SCLS007D – MARCH 1984 – REVISED AUGUST 2003

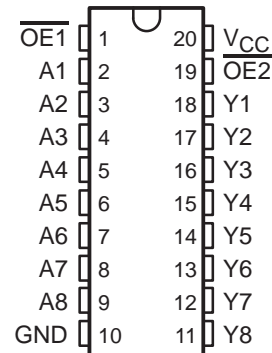
- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Outputs Drive Bus Lines Directly or Up To 15 LSTTL Loads
- Low Power Consumption, 80- $\mu$ A Max  $I_{CC}$
- Typical  $t_{pd} = 8$  ns
- $\pm 6$ -mA Output Drive at 5 V
- Low Input Current of 1  $\mu$ A Max
- Data Flow-Through Pinout (All Inputs on Opposite Side From Outputs)

## description/ordering information

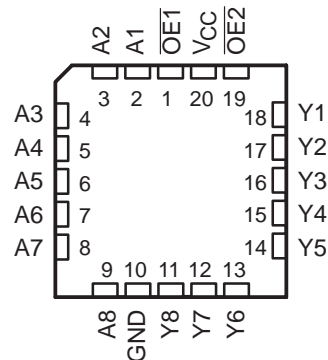
These octal buffers and line drivers feature the performance of the popular 'HC240 series and offer a pinout with inputs and outputs on opposite sides of the package. This arrangement greatly facilitates printed circuit board layout.

The 3-state control gate is a 2-input NOR. If either output-enable ( $\overline{OE1}$  or  $\overline{OE2}$ ) input is high, all eight outputs are in the high-impedance state. The 'HC540 devices provide inverted data at the outputs.

SN54HC540 . . . J OR W PACKAGE  
SN74HC540 . . . DB, DW, N, NS, OR PW PACKAGE  
(TOP VIEW)



SN54HC540 . . . FK PACKAGE  
(TOP VIEW)



## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube of 20	SN74HC540N	SN74HC540N
	SOIC – DW	Tube of 25	SN74HC540DW	HC540
		Reel of 2000	SN74HC540DWR	
	SOP – NS	Reel of 2000	SN74HC540NSR	HC540
	SSOP – DB	Reel of 2000	SN74HC540DBR	HC540
	TSSOP – PW		Tube of 70	SN74HC540PW
Reel of 2000			SN74HC540PWR	
Reel of 250			SN74HC540PWT	
-55°C to 125°C	CDIP – J	Tube of 20	SNJ54HC540J	SNJ54HC540J
	CFP – W	Tube of 85	SNJ54HC540W	SNJ54HC540W
	LCCC – FK	Tube of 55	SNJ54HC540FK	SNJ54HC540FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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 **TEXAS  
INSTRUMENTS**

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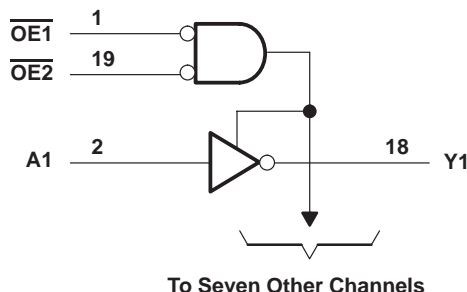
# SN54HC540, SN74HC540 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

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FUNCTION TABLE  
(each buffer/driver)

INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	A	Y
L	L	L	H
L	L	H	L
H	X	X	Z
X	H	X	Z

## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$ .....	-0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1) .....	$\pm 20$ mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1) .....	$\pm 20$ mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) .....	$\pm 35$ mA
Continuous current through $V_{CC}$ or GND .....	$\pm 70$ mA
Package thermal impedance, $\theta_{JA}$ (see Note 2):	
DB package .....	70°C/W
DW package .....	58°C/W
N package .....	69°C/W
NS package .....	60°C/W
PW package .....	83°C/W
Storage temperature range, $T_{stg}$ .....	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.

# SN54HC540, SN74HC540 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

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## recommended operating conditions (see Note 3)

		SN54HC540			SN74HC540			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	2	5	6	2	5	6	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2 V		1.5	1.5		V	
		V <sub>CC</sub> = 4.5 V		3.15	3.15			
		V <sub>CC</sub> = 6 V		4.2	4.2			
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2 V			0.5	0.5	V	
		V <sub>CC</sub> = 4.5 V			1.35	1.35		
		V <sub>CC</sub> = 6 V			1.8	1.8		
V <sub>I</sub>	Input voltage	0		V <sub>CC</sub>	0	V <sub>CC</sub>	V	
V <sub>O</sub>	Output voltage	0		V <sub>CC</sub>	0	V <sub>CC</sub>	V	
Δt/Δv	Input transition rise/fall time	V <sub>CC</sub> = 2 V			1000	1000	ns	
		V <sub>CC</sub> = 4.5 V			500	500		
		V <sub>CC</sub> = 6 V			400	400		
T <sub>A</sub>	Operating free-air temperature	-55		125	-40	85	°C	

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54HC540		SN74HC540		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -20 μA	2 V	1.9	1.998		1.9	1.9	V		
			4.5 V	4.4	4.499		4.4	4.4			
			6 V	5.9	5.999		5.9	5.9			
		I <sub>OH</sub> = -6 mA	4.5 V	3.98	4.3		3.7	3.84			
		I <sub>OH</sub> = -7.8 mA	6 V	5.48	5.8		5.2	5.34			
V <sub>OL</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 20 μA	2 V		0.002	0.1		0.1	0.1	V	
			4.5 V		0.001	0.1		0.1	0.1		
			6 V		0.001	0.1		0.1	0.1		
		I <sub>OL</sub> = 6 mA	4.5 V		0.17	0.26		0.4	0.33		
		I <sub>OL</sub> = 7.8 mA	6 V		0.15	0.26		0.4	0.33		
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0		6 V		±0.1	±100		±1000	±1000	nA	
I <sub>OZ</sub>	V <sub>O</sub> = V <sub>CC</sub> or 0		6 V		±0.01	±0.5		±10	±5	μA	
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0, I <sub>O</sub> = 0		6 V			8		160	80	μA	
C <sub>i</sub>			2 V to 6 V		3	10		10	10	pF	



# SN54HC540, SN74HC540 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range,  $C_L = 50 \text{ pF}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			SN54HC540		SN74HC540		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	Y	2 V		35	100		149		125	ns
			4.5 V		10	20		30		25	
			6 V		8	17		25		21	
$t_{en}$	$\overline{OE}$	Y	2 V		75	150		224		188	ns
			4.5 V		15	30		45		38	
			6 V		13	26		38		32	
$t_{dis}$	$\overline{OE}$	Y	2 V		40	150		224		188	ns
			4.5 V		18	30		45		38	
			6 V		17	26		38		32	
$t_t$		Y	2 V		28	60		90		75	ns
			4.5 V		8	12		18		15	
			6 V		6	10		15		13	

switching characteristics over recommended operating free-air temperature range,  $C_L = 150 \text{ pF}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			SN54HC540		SN74HC540		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	Y	2 V		60	150		224		188	ns
			4.5 V		15	30		45		38	
			6 V		13	26		38		32	
$t_{en}$	$\overline{OE}$	Y	2 V		100	200		298		250	ns
			4.5 V		20	40		60		50	
			6 V		17	34		51		43	
$t_t$		Y	2 V		45	210		315		265	ns
			4.5 V		17	42		63		53	
			6 V		13	36		53		45	

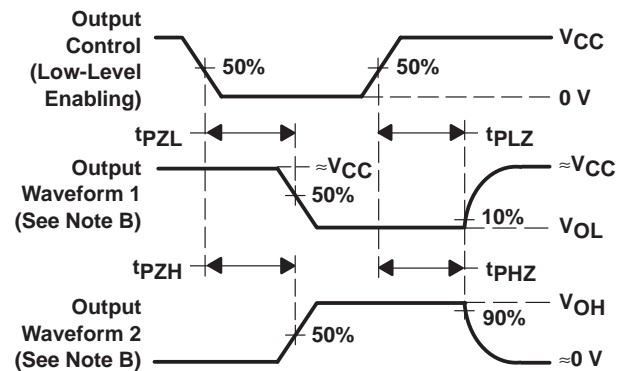
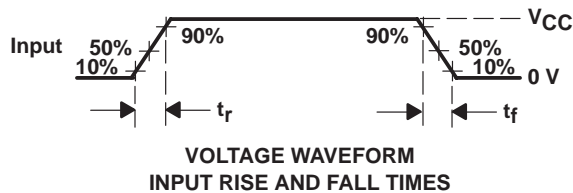
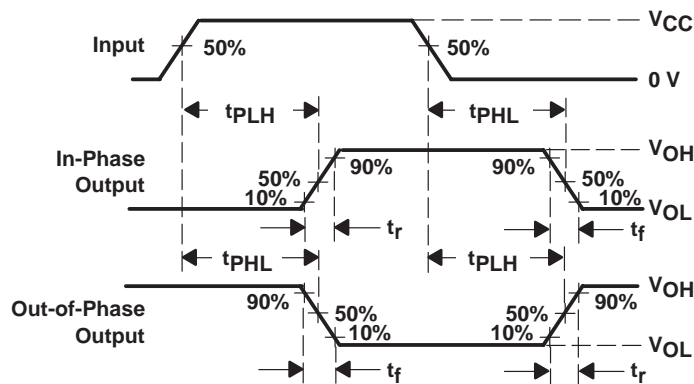
operating characteristics,  $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{pd}$ Power dissipation capacitance per buffer/driver	No load	35	pF

PARAMETER MEASUREMENT INFORMATION



PARAMETER	$R_L$	$C_L$	S1	S2
$t_{en}$	$t_{PZH}$	50 pF or 150 pF	Open	Closed
	$t_{PZL}$		Closed	Open
$t_{dis}$	$t_{PHZ}$	50 pF	Open	Closed
	$t_{PLZ}$		Closed	Open
$t_{pd}$ or $t_t$	--	50 pF or 150 pF	Open	Open



- NOTES:
- A.  $C_L$  includes probe and test-fixture capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1$  MHz,  $Z_O = 50 \Omega$ ,  $t_r = 6$  ns,  $t_f = 6$  ns.
  - D. The outputs are measured one at a time with one input transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/65710BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 65710BRA	<a href="#">Samples</a>
M38510/65710BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 65710BRA	<a href="#">Samples</a>
SN54HC540J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54HC540J	<a href="#">Samples</a>
SN74HC540DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC540	<a href="#">Samples</a>
SN74HC540DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC540	<a href="#">Samples</a>
SN74HC540DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC540	<a href="#">Samples</a>
SN74HC540DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC540	<a href="#">Samples</a>
SN74HC540DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC540	<a href="#">Samples</a>
SN74HC540N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC540N	<a href="#">Samples</a>
SN74HC540NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC540N	<a href="#">Samples</a>
SN74HC540NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC540	<a href="#">Samples</a>
SN74HC540NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC540	<a href="#">Samples</a>
SN74HC540PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC540	<a href="#">Samples</a>
SN74HC540PWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC540	<a href="#">Samples</a>
SN74HC540PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC540	<a href="#">Samples</a>
SN74HC540PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC540	<a href="#">Samples</a>
SN74HC540PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC540	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC540PWT	ACTIVE	TSSOP	PW	20	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC540	<a href="#">Samples</a>
SN74HC540PWTG4	ACTIVE	TSSOP	PW	20	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC540	<a href="#">Samples</a>
SNJ54HC540J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54HC540J	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN54HC540, SN74HC540 :**

- Catalog: [SN74HC540](#)
- Military: [SN54HC540](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications



**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC540DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74HC540NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74HC540PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
SN74HC540PWT	TSSOP	PW	20	250	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC540DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74HC540NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74HC540PWR	TSSOP	PW	20	2000	367.0	367.0	38.0
SN74HC540PWT	TSSOP	PW	20	250	367.0	367.0	38.0

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - $\triangle D$  The 20 pin end lead shoulder width is a vendor option, either half or full width.

# DW0020A



# PACKAGE OUTLINE

## SOIC - 2.65 mm max height

SOIC



4220724/A 05/2016

**NOTES:**

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



# EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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